

ABSTRACT

This user's guide describes the evaluation module (EVM) for the TPS25984B eFuse. The TPS25984B device is a 4.5V to 16V and 70A (peak) stackable eFuse with accurate and fast current monitor. This device supports parallel connection of multiple eFuses for higher current designs by actively synchronizing the device states and sharing the loads during start-up and steady-state. The TPS25984B eFuse has an integrated FET with ultra-low ON resistance of 0.8mΩ, adjustable and robust overcurrent and short-circuit protections, precise load current monitoring, fast overvoltage protection (fixed 16.7V threshold), adjustable output slew rate control for inrush-current protection, and overtemperature protection to verify FET SOA. The TPS25984B eFuse also has fixed overcurrent transient blanking timer to support load transients, adjustable undervoltage protection, integrated FET health monitoring and reporting, analog die temperature monitor output, and dedicated fault and power good indication pins.

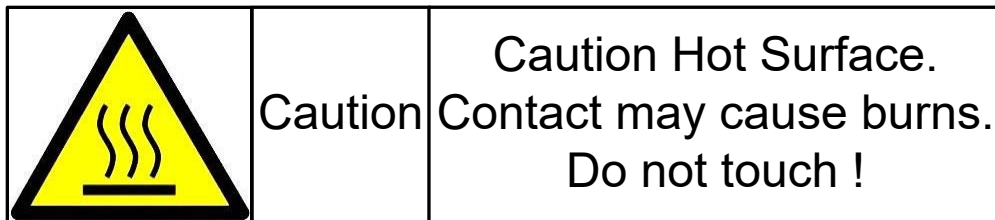


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1 Introduction

The TPS25984BEVM eFuse evaluation board allows reference circuit evaluation of Texas Instruments (TI) TPS25984B eFuse. The TPS25984B device is a 4.5V to 16V and 70A (peak) stack-able eFuse with accurate and fast current monitor. This device supports parallel connection of multiple eFuses for higher current designs by actively synchronizing the device states and sharing the loads during start-up and steady-state. The TPS25984B eFuse has an integrated FET with ultra-low ON resistance of 0.8mΩ, adjustable and robust overcurrent and short-circuit protections, precise load current monitoring, fast overvoltage protection (fixed 16.7V threshold), adjustable output slew rate control for inrush current protection, and over-temperature protection to verify FET SOA. The TPS25984B eFuse also has fixed overcurrent transient blanking timer to support load transients, adjustable undervoltage protection, integrated FET health monitoring and reporting, analog die temperature monitor output, and dedicated fault and power good indication pins.

1.1 EVM Features

TPS25984BEVM comes with two (2) TPS25984B eFuses connected in parallel to evaluate a 12V (typical) and 110A (steady-state) design. TPS25984BEVM eFuse evaluation board features include:

- 5V to 16V (typical) operation
- 14A to 120A programmable circuit breaker threshold using onboard jumpers
- Adjustable reference voltage for overcurrent protection and active current sharing blocks
- Adjustable output voltage slew rate control
- Fixed transient current blanking timer
- Adjustable current limit during start-up and active current sharing threshold using onboard jumpers
- TVS diode for input and Schottky diode for output transient protections
- LED status for power good and fault indications
- Options to engage the power cycle and the quick output discharge (QOD)
- Option to apply custom load transients using onboard MOSFETs, gate drive circuit, and load resistors

1.2 EVM Applications

This EVM can be used on the following applications:

- Input hotswap and hotplug
- [Server](#) and [high performance computing](#)
- [Network interface cards](#)
- [Graphics and hardware accelerator cards](#)
- [Datacenter switches](#) and [routers](#)
- Fan trays
- Switches/routers

2 Description

The TPS25984BEVM enables the evaluation of TPS25984B0 eFuses from TPS25984B family. This EVM has two (2) TPS25984B0 eFuses connected in parallel. The input power is applied across the connectors T1 and T3, while T2 and T3 provide the output connection for the EVM; refer to the schematic in [Figure 3-1](#) and EVM test setup in [Figure 5-1](#). TVS diodes D1 and D2 provide the input protection from transient overvoltages. Schottky diodes D3 and D4 protect the output by clamping the negative voltage excursion at the OUT pins of TPS25984B eFuses within the minimum absolute rating.

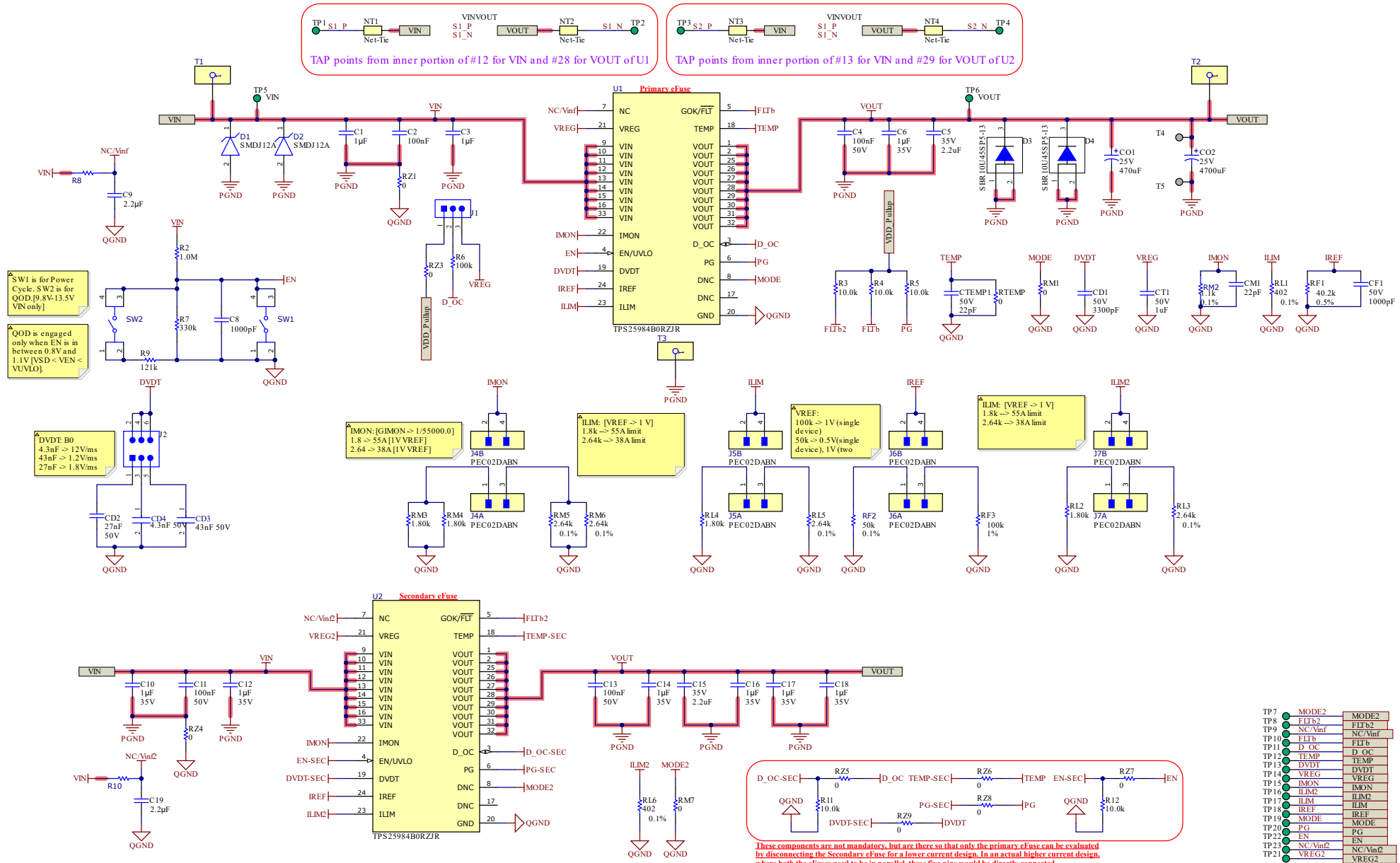
SW1 allows to do power cycle and SW2 enables the quick output discharge (QOD). Power Good (PG) and fault (FLTb and FLTb2) indicators are provided by LED DG1, DR1, and DR2 respectively.

Table 2-1. TPS25984BEVM eFuse Evaluation Board Options and Setting

EVM Function	V _{IN} UVLO Threshold	V _{IN} OVLO Threshold	Output Slew Rate (dv/dt)	IMON	ILIM	ILIM2	IREF
Performance evaluation of TPS25984B, 4.5V to 16V, 55A (RMS) eFuse	5V	16.7V	Selectable - 1.2V/ms, 1.8V/ms, and 12V/ms	Selectable - 110A and 75A for V _{IMON} of 1V	Selectable - 29A and 20A of inrush current limit and 55A and 38A of steady state current limit threshold with V _{REF} of 1V	Selectable - 1V and 0.5V	Selectable - 1V and 0.5V

3 Schematic

Figure 3-1 illustrates the EVM schematic.



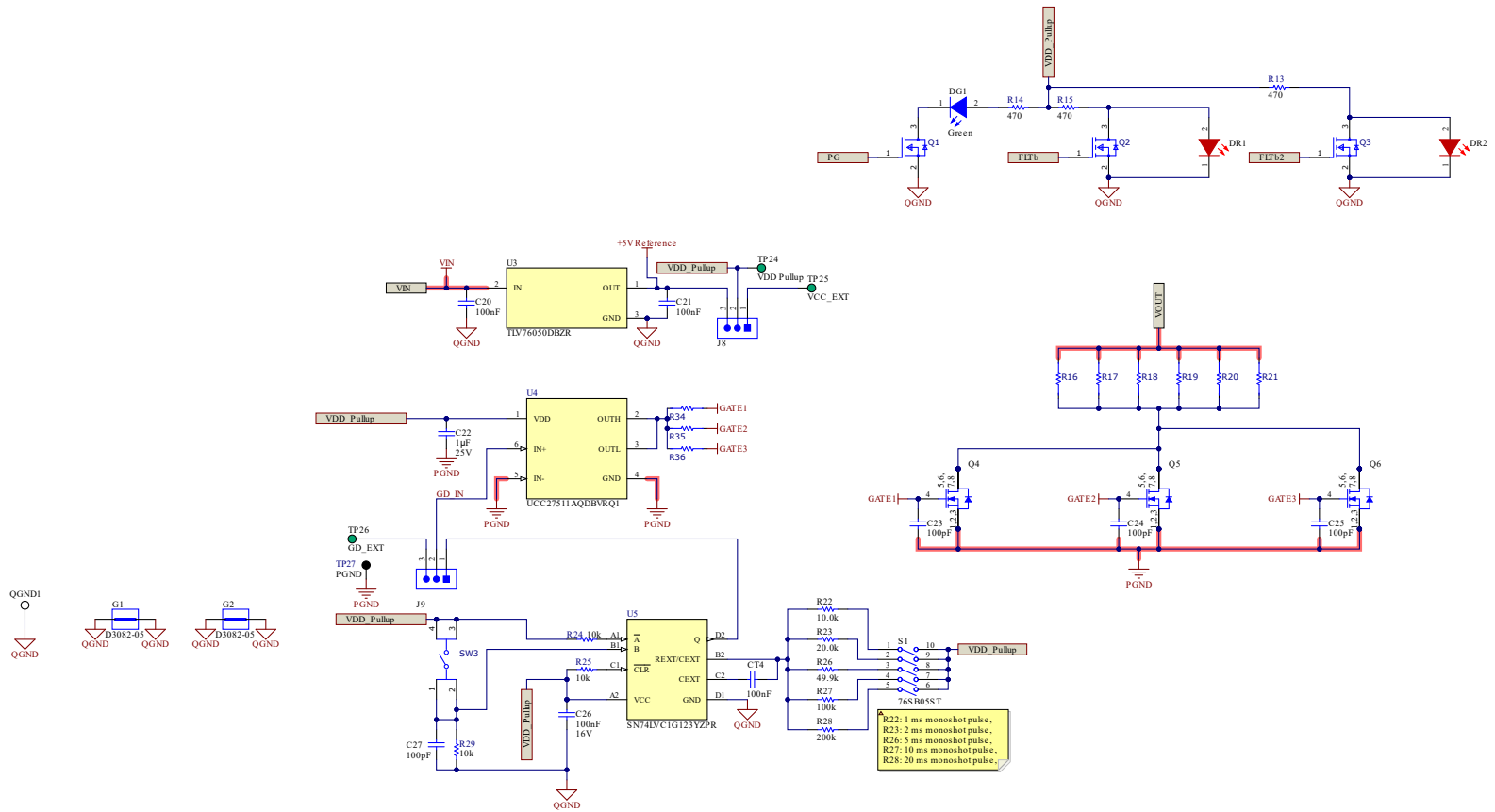


Figure 3-2. TPS25984BEVM eFuse Evaluation Board Schematic (Page 2)

Note

- To evaluate the performance of one TPS25984B eFuse at lower currents (< 55A), RZ5, RZ6, RZ7, RZ8, and RZ9 resistors need to be depopulated. Also R11 and R12 resistors must be populated to disable the secondary eFuse.
 - The ground connections for the various components around the TPS25984B eFuses must be wired directly to each other and the GND pins of respective eFuses. This must be followed by connecting them to the system ground at one point, as implemented using RZ1 and RZ4 resistors in the EVM schematic. Do not connect the various component grounds through the high current system ground line.
-

4 General Configurations

4.1 Physical Access

Table 4-1 lists the TPS25984BEVM eFuse Evaluation Board input and output connectors functionalities. Table 4-2 and Table 4-3 describe the availability of test points and the functionalities of the jumpers. Table 4-4 presents the functions of the signal LEDs.

Table 4-1. Input and Output Connector Functionality

Connector	Label	Description
T1	VIN (+)	Positive terminal for the input power to the EVM
T2	VOUT (+)	Positive terminal for the output power from the EVM
T3	PGND (-)	Negative terminal for the EVM (Common for both input and output)

Table 4-2. Test Points Description

Test Points	Label	Description
TP1	S1_P	Kelvin sensing points to measure on-resistance: Primary Device (U1)
TP2	S1_N	
TP3	S2_P	Kelvin sensing points to measure on-resistance: Secondary Device (U2)
TP4	S2_N	
TP5	VIN	Input Voltage
TP6	VOUT	Output Voltage
TP7	MODE2	MODE selection: Secondary Device
TP8	FLTb2	Open-drain active low fault indication: Primary Device
TP9	NC/Vinf	Pin 7 from Primary Device
TP10	FLTb	Open-drain active low fault indication: Primary Device
TP11	D_OC	Open-drain signal to indicate and control power switch ON and OFF status
TP12	TEMP	Maximum device die temperature monitor analog voltage output with two (2) TPS25984B eFuses in parallel
TP13	DVDT	Start-up output slew rate control
TP14	VREG	Internal LDO output from Primary device
TP15	IMON	Load current monitor and overcurrent and fast-trip thresholds during steady state
TP16	ILIM2	Current limit and fast-trip threshold during start-up: Secondary Device
TP17	ILIM	Current limit and fast-trip threshold during start-up: Primary Device
TP18	IREF	Reference voltage for overcurrent and short-circuit protections, and active current sharing blocks
TP19	MODE	MODE selection: Primary Device
TP20	PG	Open-drain active high power good indication
TP21	VREG2	Internal LDO output from Secondary device
TP22	EN	Active high enable input
TP23	NC/Vinf2	Pin 7 from Secondary Device
TP24	VDD PULLUP	5V pullup power supply generated using a LDO from VIN
TP25	VCC EXTERNAL	External pullup power supply
TP26	GD EXTERNAL	External gate signal for custom load transient
TP27	PGND	Supply Ground

Table 4-2. Test Points Description (continued)

Test Points	Label	Description
QGND1	QGND	Device Ground
G1	QGND	
G2	QGND	

Table 4-3. Jumper Descriptions and Default Positions

Jumper	Label	Description	Default Jumper Position
J1	D_OC	1-2 Position: The D_OC pull-up supply is generated from VIN using a LDO Through a 100kΩ resistor	1-2
		2-3 Position: The D_OC pin is connected to the VREG (internal LDO from the device) of the Primary Device through a 100kΩ resistor	
J2	DVDT	1-2 Position sets the output slew rate to 1.8V/ms	5-6
		3-4 Position sets the output slew rate to 12V/ms	
		5-6 Position sets the output slew rate to 1.2V/ms	
J4	IMON	1-2 Position sets the V_{IMON} to 1V at 110A	1-2
		3-4 Position sets the V_{IMON} to 1V at 75A	
J5	ILIM	1-2 Position sets the inrush current limit to 29A and the active current sharing threshold to 55A with V_{IREF} of 1V: Primary Device	1-2
		3-4 Position sets the inrush current limit to 20A and the active current sharing threshold to 38A with V_{IREF} of 1V: Primary Device	
J6	IREF	1-2 Position sets the reference voltage for overcurrent and short-circuit protection blocks to 1V when testing with two devices or 0.5V when only testing with Primary device	3-4
		3-4 Position sets the reference voltage for overcurrent and short-circuit protection blocks to 2V when testing with two devices or 1V when only testing with Primary device	
J7	ILIM2	1-2 Position sets the inrush current limit to 29A and the active current sharing threshold to 55A with V_{IREF} of 1V: Secondary Device	1-2
		3-4 Position sets the inrush current limit to 20A and the active current sharing threshold to 38A with V_{IREF} of 1V: Secondary Device	
J8	VDD PULL-UP POWER SUPPLY	1-2 Position provides the VDD pull-up supply from the external power source	2-3
		2-3 Position provides the VDD pull-up supply from the onboard 12V to 5V LDO	
J9	EXTERNAL GATE SIGNAL	1-2 Position provides the GATE signal to the MOSFETs (Q4 – Q6) from the onboard mono-shot	1-2
		2-3 Position provides the GATE signal to the MOSFETs (Q4 – Q6) from the external signal generator	

Table 4-4. LED Descriptions

LED	Description
DG1	When ON, indicates that PG is asserted
DR1	When ON, indicates that FLTb is asserted
DR2	When ON, indicates that FLTb2 is asserted

4.2 Test Equipment

4.2.1 Power Supplies

One adjustable power supply with 0V to 30V output and 0A to 200A output current limit.

4.2.2 Meters

Minimum of a Digital Multi Meter (DMM) needed.

4.2.3 Oscilloscope

A DPO2024 or equivalent, three 10x voltage probes, and a DC current probe.

4.2.4 Loads

One resistive load or equivalent which can tolerate up to 200A DC load at 24V and capable of the output short.

5 Test Setup and Procedures

In this user's guide, the test procedure is described for TPS25984B eFuse. Make sure the evaluation board has default jumper settings as shown in [Table 5-1](#).

Table 5-1. Default Jumper Setting for TPS25984BEVM eFuse Evaluation Board

J1	J2	J4	J5	J6	J7	J8	J9
1-2	5-6	1-2	1-2	1-2	1-2	2-3	1-2

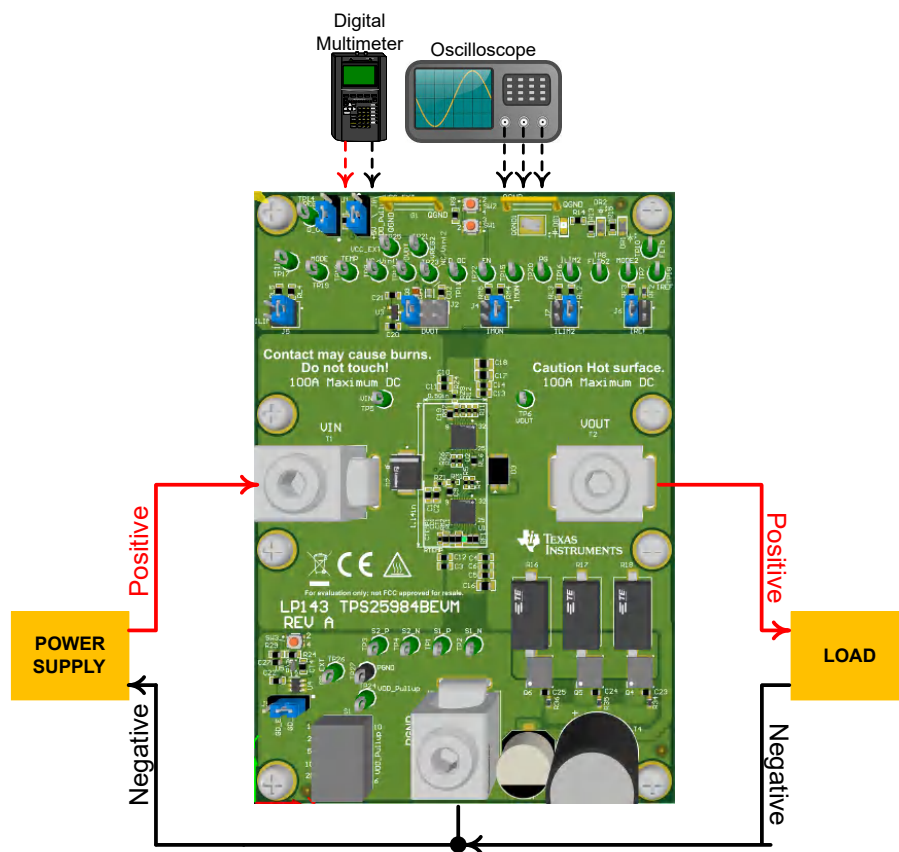


Figure 5-1. TPS25984BEVM Setup With Test Equipment

Follow these instructions before starting any test and repeat again before moving to the next test:

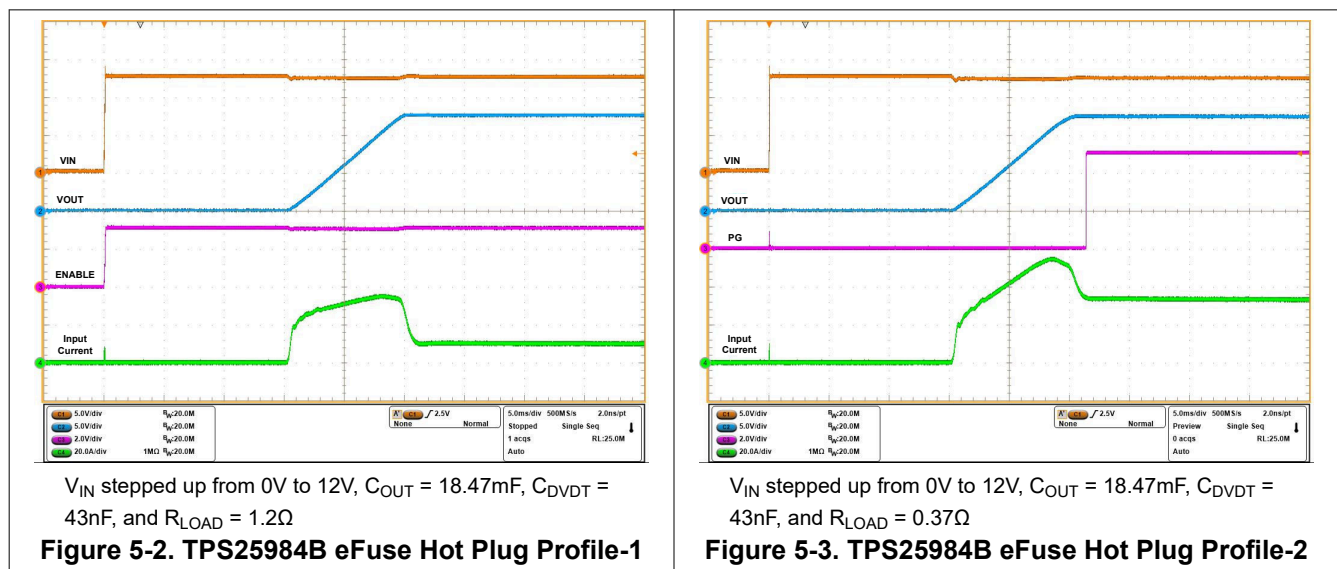
- Set the power supply output (VIN) to zero volts.
- Turn off the power supply.
- Adjust the jumper positions on EVM to the default configuration as shown in [Table 5-1](#).
- Turn the power supply on and set the power supply output (VIN) to 12V, 200A, and keep the power supply output disabled.
- Enable the power supply output so that the EVM gets the input power supply.

5.1 Hot Plug

Use the following instructions to measure the inrush current during hot plug event:

1. Configure the jumper J2 position to the desired slew rate mentioned in [Table 4-3](#).
2. Configure the jumpers J5 and J7 positions to the desired current limits as mentioned in [Table 4-3](#).
3. Configure the jumper J6 position to desired reference voltage for overcurrent protection as specified in [Table 4-3](#).
4. Connect a load of 1.2Ω between VOUT (Connector T2) and PGND (Connector T3).
5. Connect the negative terminal of the power supply to connector T3.
6. Set the input supply voltage VIN to 12V and current limit to 100A. Enable the power supply.
7. Hot plug the positive terminal of the power supply at connector T1.
8. Observe the waveforms at VOUT (TP6) and input current using an oscilloscope to measure the slew rate and rise time of the VOUT with a given input voltage of 12V.

[Figure 5-2](#) and [Figure 5-3](#) show the examples of inrush current captured on the TPS25984BEVM eFuse evaluation board with two (2) devices in parallel during the hot plug event.

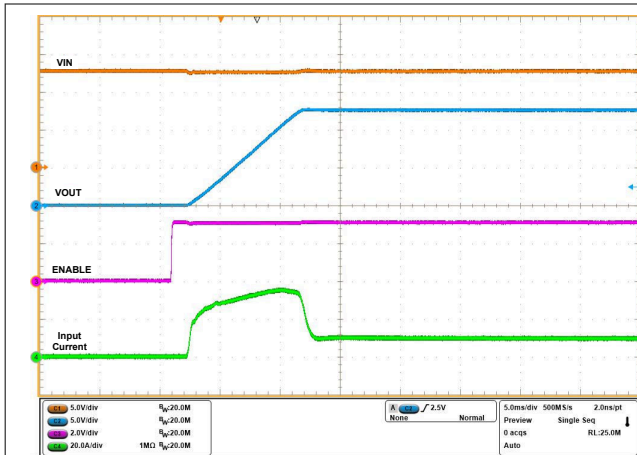


5.2 Start-Up With Enable

Use the following instructions to power up the TPS25984B eFuse with ENABLE:

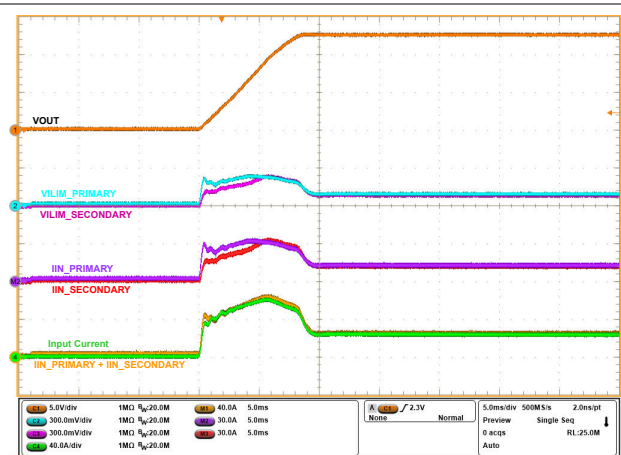
1. Configure the jumper J2 position to the desired slew rate mentioned in [Table 4-3](#).
2. Configure the jumpers J5 and J7 positions to the desired current limits as mentioned in [Table 4-3](#).
3. Configure the Jumper J6 position to desired reference voltage for overcurrent protection as mentioned in [Table 4-3](#).
4. Set the input supply voltage VIN to 12V and current limit to 100A.
5. Connect a load of 1.2Ω between VOUT (Connector T2) and PGND (Connector T3).
6. Connect the input supply between VIN (Connector T1) and PGND (Connector T3).
7. Turn on the power supply by keeping the device disabled using the switch SW1.
8. Enable the eFuses by releasing the switch SW1.
9. Observe the waveform at VOUT (TP6) and input current using an oscilloscope to measure the slew rate and rise time of the VOUT with a given input voltage of 12V.

[Figure 5-4](#) and [Figure 5-5](#) show the start-up profile of TPS25984B eFuse with ENABLE using two (2) devices in parallel.



$V_{IN} = 12V$, EN stepped up from 0V to 3V, $C_{OUT} = 18.47mF$,
 $R_{LOAD} = 1.2\Omega$, and $C_{DVDT} = 43nF$

Figure 5-4. TPS25984B eFuse Start-Up Profile With ENABLE



$V_{IN} = 12V$, EN stepped up from 0V to 3V, $R_{ILIM} = 1.65k\Omega$, $R_{LIM2} = 1.65k\Omega$, $R_{REF} = 50k\Omega$, $C_{OUT} = 25.27mF$, $R_{LOAD} = 0.5\Omega$, and $C_{DVDT} = 27nF$

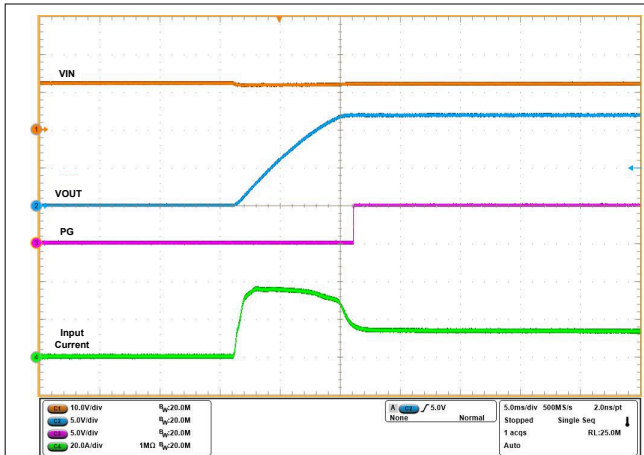
Figure 5-5. Start-Up Profile With ENABLE: Current Sharing Between Two (2) TPS25984B eFuses

5.3 Difference Between Current Limit and DVDT Based Start-Up Mechanisms

Use the following instructions to perform the start-up with current limit test:

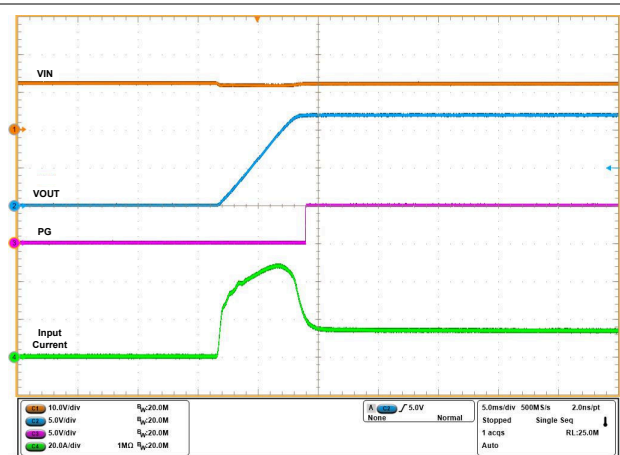
1. Configure the jumper J2 position to the desired slew rate mentioned in [Table 4-3](#).
2. Configure the jumpers J5 and J7 positions to the desired current limits as mentioned in [Table 4-3](#).
3. Configure the Jumper J6 position to desired reference voltage for overcurrent protection as mentioned in [Table 4-3](#).
4. Set the input supply voltage V_{IN} to 12V and current limit to 100A.
5. Connect a load of 0.9Ω between VOUT (Connector T2) and PGND (Connector T3).
6. Connect the input supply between V_{IN} (Connector T1) and PGND (Connector T3).
7. Turn on the power supply by keeping the device disabled using the switch SW1.
8. Enable the eFuse by releasing the switch SW1.
9. Observe the waveform at VOUT (TP6) and input current using an oscilloscope. The main intention of this experiment is to observe the output voltage and input current profiles and time required to complete the inrush with two different ILIM set points having all other test conditions identical. The inrush current hits the current limit set point in one case, but does not in the next.

[Figure 5-6](#) and [Figure 5-7](#) show the difference between the current limit and DVDT based start-up mechanisms on the TPS25984BEVM eFuse evaluation board having two (2) devices in parallel for R_{ILIM} of $2.8k\Omega$, R_{LIM2} of $2.8k\Omega$, R_{ILIM} of $1.65k\Omega$, and R_{LIM2} of $1.65k\Omega$.



$V_{IN} = 12V$, EN stepped up from 0V to 3V, $R_{LIM1} = 2.8k\Omega$, $R_{LIM2} = 2.8k\Omega$, $R_{REF} = 50k\Omega$, $C_{OUT} = 18.47mF$, $R_{LOAD} = 0.9\Omega$, and $C_{DVDT} = 43nF$

Figure 5-6. Start-Up With Current Limit Response of TPS25984B eFuse



$V_{IN} = 12V$, EN stepped up from 0V to 3V, $R_{LIM1} = 1.65k\Omega$, $R_{LIM2} = 1.65k\Omega$, $R_{REF} = 50k\Omega$, $C_{OUT} = 18.47mF$, $R_{LOAD} = 0.9\Omega$, and $C_{DVDT} = 43nF$

Figure 5-7. Start-Up With Output Slew Rate Control (Only) Response of TPS25984B eFuse

5.4 Power Up Into Short

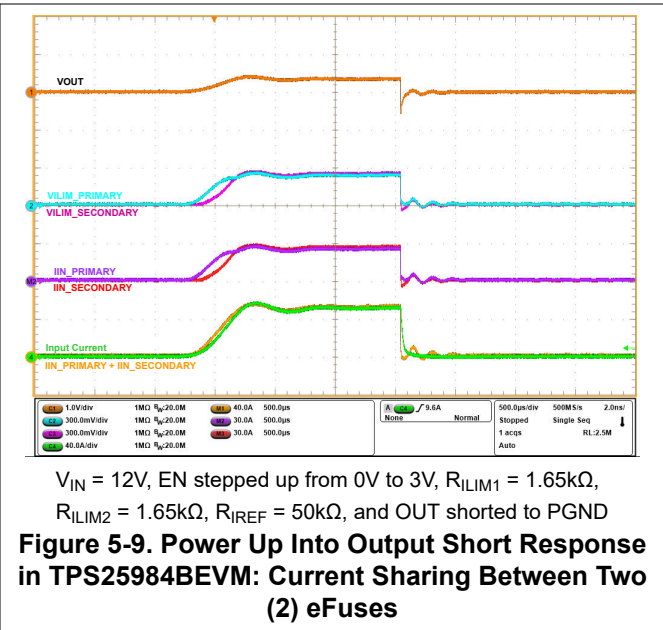
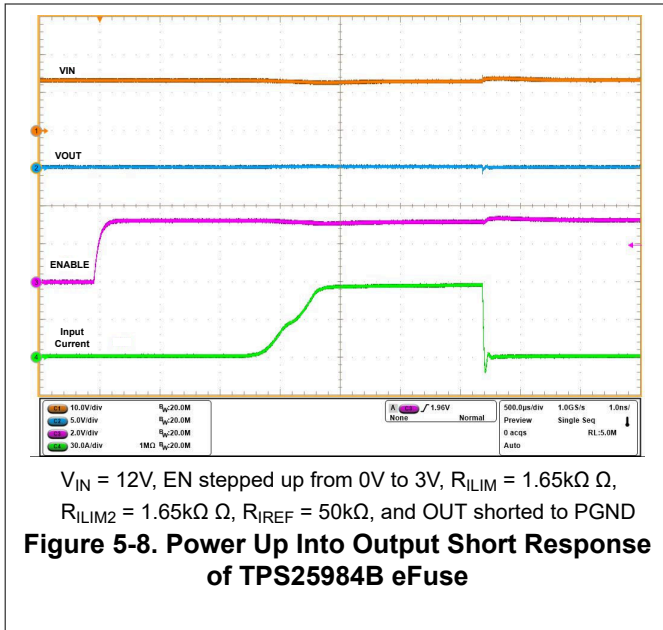
Use the following instructions to perform the power up into short test:

1. Set the input supply voltage V_{IN} to 12V and current limit to 100A. Connect the supply between V_{IN} (Connector T1) and PGND (Connector T3) and keep the power supply OFF.
2. Short the output of the EVM. For example, V_{OUT} (Connector T2) to PGND (Connector T3) through a short and thick cable to make sure the short-circuited path impedance is minimum as possible.
3. Configure the Jumper J6 position to desired reference voltage for overcurrent protection as mentioned in [Table 4-3](#).
4. Configure the jumpers J5 and J7 positions to the desired current limits as mentioned in [Table 4-3](#).
5. Keep the TPS25984B eFuses disabled by pushing the switch SW1.
6. Turn ON the power supply.
7. Enable the TPS25984B eFuse by releasing the switch SW1.

Figure 5-8 and Figure 5-9 show the test waveforms of power up into output short on the TPS25984BEVM eFuse Evaluation Board with two (2) devices in parallel.

Note

During power up into short, a thermal fold-back results in the current flowing through the device being less than the calculated value of the current limit during start-up.



5.5 Overvoltage Lockout

Use the following instructions to perform the overvoltage protection test:

1. Set the input supply voltage V_{IN} to 12V and current limit to 100A. Apply the supply between V_{IN} (Connector T1) and PGND (Connector T3) and enable the power supply.
2. Apply a load of 1.2Ω between V_{OUT} (Connector T2) and PGND (Connector T3).
3. Increase the input supply V_{IN} from 12V to 18V and observe the waveforms using an oscilloscope.

Figure 5-10 shows overvoltage lockout response of TPS25984B eFuse on TPS25984BEVM eFuse Evaluation Board.

Note

The input TVS diodes must be removed during the overvoltage protection test. Make sure to put the diodes back after this experiment.

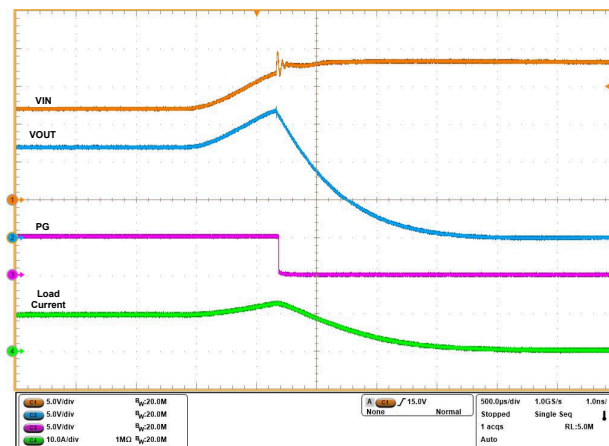


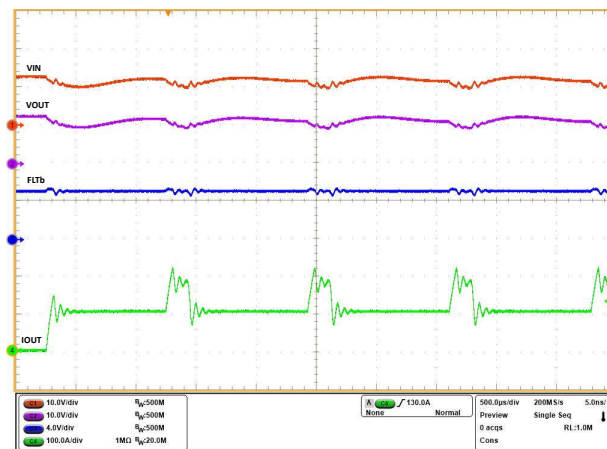
Figure 5-10. Overvoltage Lockout Response of TPS25984B eFuse

5.6 Transient Overload Performance

Use the following instructions to observe the transient overload performance:

1. Configure the Jumper J6 position to desired reference voltage for overcurrent protection as mentioned in [Table 4-3](#).
2. Configure the Jumper J5 and J7 in a good position to set required current limiting threshold (I_{OCP}) as per [Table 4-3](#).
3. Connect an electronic load (capable of applying load transients of up to 200A) between VOUT (Connector T2) and PGND (Connector T3) and leave the load disabled.
4. Set the input supply voltage V_{IN} to 12V and current limit of 200A.
5. Connect the power supply between V_{IN} (Connector T1) and PGND (Connector T3) and enable the power supply.
6. Now apply an overload using the electronic load in the range of $I_{OCP} < I_{LOAD} < 2 \times I_{OCP}$ for a time duration less than $250\mu s$ (blanking timer duration)
7. Observe the waveforms using an oscilloscope.

[Figure 5-11](#) shows transient overload performance of TPS25984B eFuse on TPS25984BEVM eFuse evaluation board with two (2) devices in parallel.



$V_{IN} = 12V$, $C_{OUT} = 470\mu F$, $R_{LIM1} = 1.78k\Omega$, $R_{LIM2} = 1.78k\Omega$, $R_{REF} = 50k\Omega$, I_{OUT} ramped from 100A to 150A then 100A within $150\mu s$

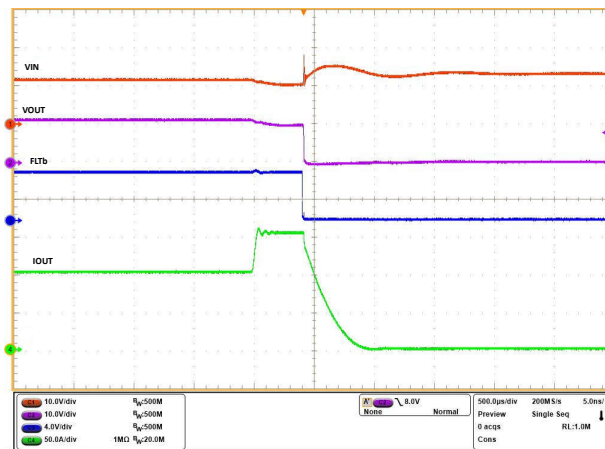
Figure 5-11. Transient Overload Performance of TPS25984B eFuse

5.7 Overcurrent Event

Use the following instructions to perform the overcurrent test on TPS25984B eFuse:

1. Configure the Jumper J6 position to desired reference voltage for overcurrent protection and active current sharing as mentioned in [Table 4-3](#).
2. Configure the Jumper J5 and J7 in a good position to set required current limiting threshold (I_{OCP}) as per [Table 4-3](#).
3. Connect an electronic load (capable of applying load transients of up to 200A) between VOUT (Connector T2) and PGND (Connector T3) and leave the load disabled.
4. Set the input supply voltage VIN to 12V and current limit of 200A.
5. Connect the power supply between VIN (Connector T1) and PGND (Connector T3) and enable the power supply.
6. Now apply an overload using the electronic load in the range of $I_{OCP} < I_{LOAD} < 2 \times I_{OCP}$ for a time duration more than 250 μ s (fixed blanking timer duration).
7. Observe the waveforms using an oscilloscope.

Figure 5-12 shows the circuit breaker response of TPS25984B eFuse on TPS25984BEVM eFuse evaluation board with two (2) devices in parallel.



$V_{IN} = 12V$, $C_{OUT} = 470\mu F$, $R_{ILIM1} = 1.78k\Omega$, $R_{ILIM2} = 1.78k\Omega$, $R_{IREF} = 50k\Omega$, I_{OUT} ramped from 100A to 150A for 20ms

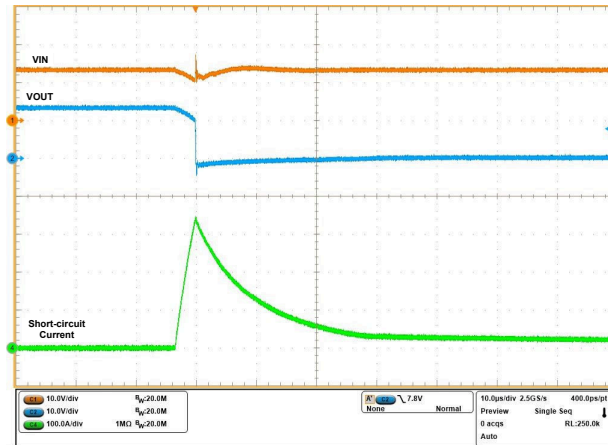
Figure 5-12. Overcurrent Performance of TPS25984B eFuse-1

5.8 Output Hot Short

Use the following instructions to perform the output hot short test:

1. Set the input supply voltage V_{IN} to 12V and connect the power supply between V_{IN} (Connector T1) and PGND (Connector T3).
2. Turn ON the power supply.
3. Short the output of the device for example, V_{OUT} (Connector T2) to PGND (Connector T3) through a shorter cable, which is just enough to insert a 150A current probe.
4. Observe the waveforms using an oscilloscope.

Figure 5-13 shows the test waveforms of output hot short on the TPS25984BEVM with two (2) TPS25984B eFuses in parallel.



$V_{IN} = 12V$, $R_{ILIM1} = 2k\Omega$, $R_{ILIM2} = 2k\Omega$, $R_{REF} = 50k\Omega$, and $C_{OUT} = 10\mu F$

Figure 5-13. Output Hot Short Response of TPS25984B eFuse

Make sure there is sufficient input capacitor to eliminate voltage dips at the input. A combination of electrolytic and ceramic capacitors are preferred. With these capacitors, a large current can be provided for a short period of time during short-circuit.

Note

Obtaining repeatable and similar short-circuit testing results is very difficult. The following contributes to the variation in results:

- Source bypassing
- Input leads
- Board layout
- Component selection
- Output shorting method
- Relative location of the short
- Instrumentation

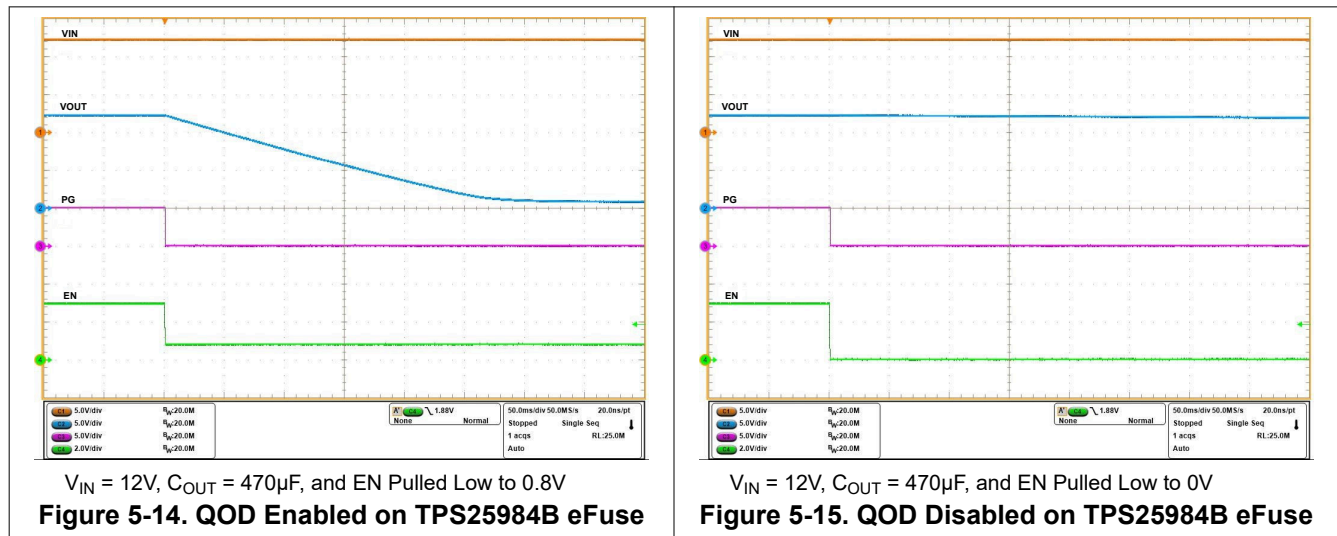
The actual short exhibits a certain degree of randomness because the short microscopically bounces and arcs. Make sure that configuration and methods are used to obtain realistic results. Hence, do not expect to see waveforms exactly like the waveforms in this user's guide because every setup is different.

5.9 Quick Output Discharge (QOD)

Use the following instructions to observe the Quick Output Discharge (QOD) functionality:

1. Set the input supply voltage V_{IN} to 12V and current limit to 10A. Turn ON the power supply.
2. Use the switch SW1 to connect the EN/UVLO pin to ground to do power cycling.
3. Use the switch SW2 to enable the QOD by making the voltage at EN/UVLO pin in the range of 0.8V–1.1V with the input voltage of 9.8V–13.5V.
4. Observe the waveforms of V_{IN} (TP5), V_{OUT} (TP6), PG (TP20), and EN (TP22) using an oscilloscope.

In [Figure 5-14](#), the turn-off performance of the TPS25984B eFuse with QOD enabled is shown, whereas [Figure 5-15](#) illustrates the turn-off performance with QOD disabled on the TPS25984BEVM eFuse evaluation board.



5.10 Thermal Performance of TPS25984BEVM

Use the following instructions to evaluate the thermal performance of TPS25984BEVM:

1. Configure the Jumper J6 position to desired reference voltage (V_{IREF}) for overcurrent protection and active current sharing as mentioned in [Table 4-3](#). The "1-2" position of the jumper J6 is selected in this experiment, which makes V_{IREF} as 1V (typical).
2. Configure the jumpers J5 and J7 in a good position to set required steady state current limit threshold (I_{OCP}) as per [Table 4-3](#). The "1-2" position of the jumpers J5 and J7 are selected in this experiment, which makes I_{OCP} as 120A (typical) with V_{IREF} as 1V (typical).
3. Set the input supply voltage V_{IN} to 12V and current limit of 115A.
4. Connect the power supply between V_{IN} (Connector T1) and PGND (Connector T3) and enable the power supply.
5. Now apply a load of 110A (DC) between V_{OUT} (Connector T2) and PGND (Connector T3) for half an hour or more to reach the thermal equilibrium point.
6. Capture the thermal image of the EVM or monitor the voltage at TEMP (TP12) pin using a digital multimeter. Voltage at the TEMP (V_{TEMP}) pin reports the maximum die temperature between two (2) TPS25984B eFuses, which can be obtained using [Equation 1](#).

$$T_J(^{\circ}C) = \left[25 + \left\{ \frac{V_{TEMP}(mV) - 677.6}{2.72 (mV/^{\circ}C)} \right\} \right] \quad (1)$$



$V_{IN} = 12V$, $I_{OUT} = 110A$, $T_A = 25^\circ C$, and no external air flow

Figure 5-16. Thermal Performance of TPS25984BEVM

Figure 5-16 shows the thermal performance of TPS25984BEVM with two (2) TPS25984B eFuses in parallel.

6 EVAL Board Assembly Drawings and Layout Guidelines

6.1 PCB Drawings

Figure 6-1 and Figure 6-2 show the component placements of the EVM. A pictorial representation of the TPS25984BEVM PCB layers can be found in Figure 6-3 to Figure 6-10.

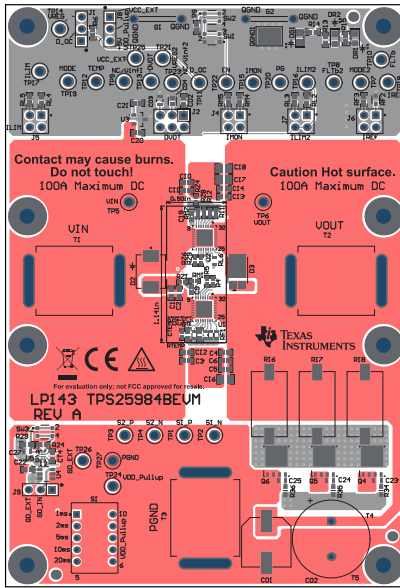


Figure 6-1. TPS25984BEVM Board: Top Assembly

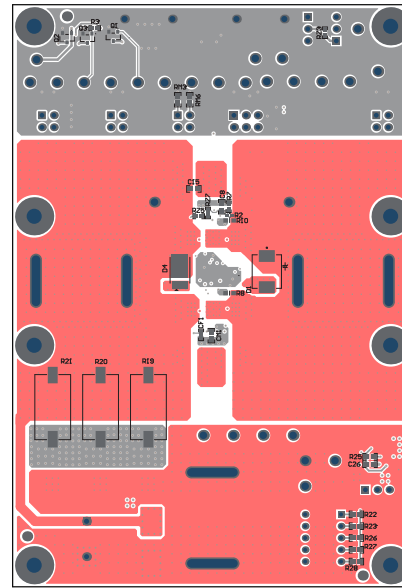


Figure 6-2. TPS25984BEVM Board: Bottom Assembly

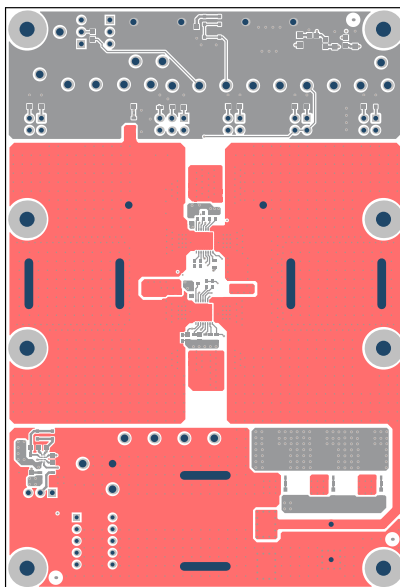


Figure 6-3. TPS25984BEVM Board: Top Layer

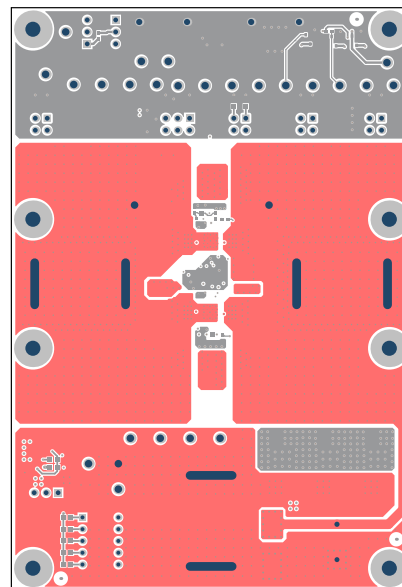


Figure 6-4. TPS25984BEVM Board: Bottom Layer

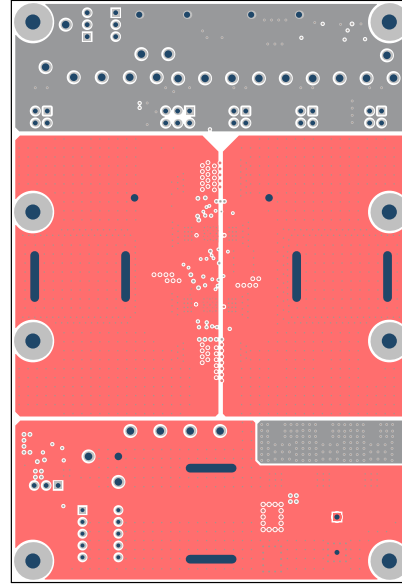
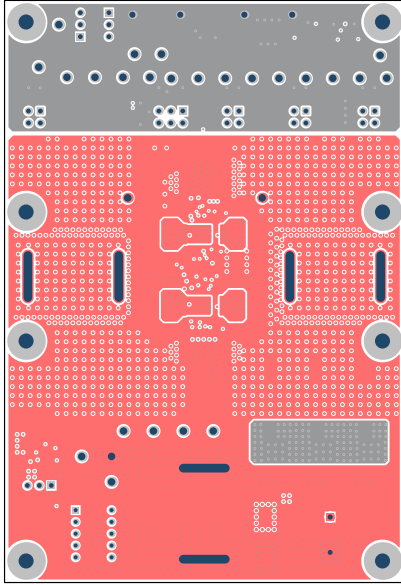


Figure 6-5. TPS25984BEVM Board: Layer 2 (Power) Figure 6-6. TPS25984BEVM Board: Layer 3 (Power)

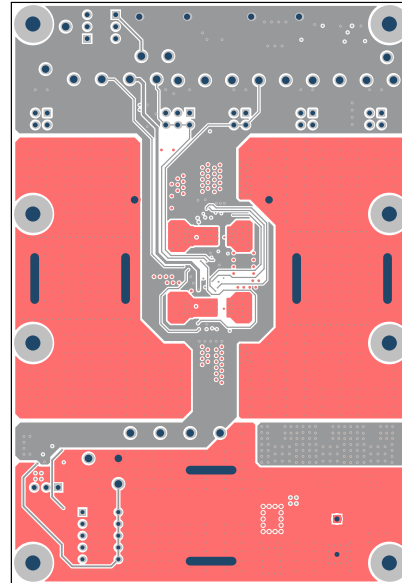
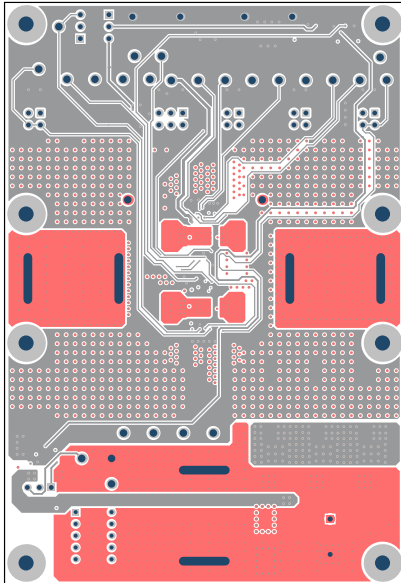


Figure 6-7. TPS25984BEVM Board: Layer 4 (Signal) Figure 6-8. TPS25984BEVM Board: Layer 5 (Signal)

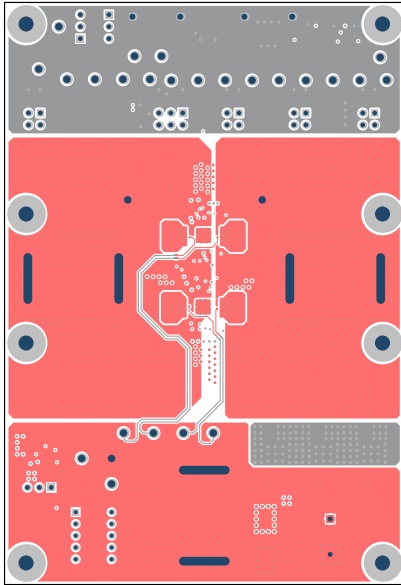


Figure 6-9. TPS25984BEVM Board: Layer 6 (Power)

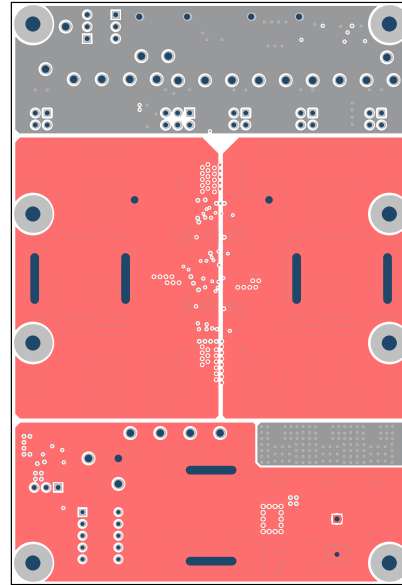


Figure 6-10. TPS25984BEVM Board: Layer 7 (Power)

Note

Analog signal nets, such as IREF, IMON, and TEMP, must be routed away as much as possible from power nets, such as VIN, VOUT, and PGND.

7 Bill of Materials (BOM)

Table 7-1 lists the EVM BOM.

Table 7-1. TPS25984BEVM Bill of Materials

Designator	Quantity	Value	Description	Footprint	PartNumber	Manufacturer	Comments
IPCB1	1		Printed Circuit Board		PSIL196	Any	
C1, C3, C6, C10, C12, C14	6	1uF	CAP, CERM, 1uF, 35V, +/- 10%, X7R, 0603	0603	C1608X7R1V105K080AC	TDK	
C2, C4, C11, C13, CT4	5	0.1uF	CAP, CERM, 0.1uF, 50V, +/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603	C0603C104K5RACAUTO	Kemet	
C5, C15	2	2.2uF	CAP, CERM, 2.2uF, 35V, +/- 10%, X5R, 0603	0603	GRM188R6YA225KA12D	MuRata	
C8	1	1000pF	CAP, CERM, 1000pF, 50V, +/- 5%, C0G/NP0, 0603	0603	GRM1885C1H102JA01D	MuRata	
C9, C19	2	2.2uF	CAP, CERM, 2.2uF, 25V, +/- 10%, X7S, 0603	0603L	GRM188C71E225KE11D	MuRata	
C16, C17, C18	3	1uF	CAP, CERM, 1uF, 35V, +/- 10%, X7R, 0805	0805_HV	GMK212B7105KG-T	Taiyo Yuden	
C20, C21	2	0.1uF	CAP, CERM, 0.1uF, 50V, +/- 10%, X7R, 0603	0603	06035C104KAT2A	AVX	
C22	1	1uF	CAP, CERM, 1uF, 25V, +/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603	GCM188R71E105KA64D	MuRata	
C23, C24, C25, C27	4	100pF	CAP, CERM, 100pF, 50V, +/- 5%, C0G/NP0, 0603	0603S	885012006057	Wurth Elektronik	
C26	1	0.1uF	CAP, CERM, 0.1uF, 16V, +/- 10%, X7R, 0603	0603	CL10B104KO8WPNC	Samsung Electro-Mechanics	
CD1	1	3300pF	CAP, CERM, 3300pF, 50V, +/- 5%, C0G/NP0, 0603	0603S	GRM1885C1H332JA01D	MuRata	
CD2	1	27nF	CAP, CERM, 0.027uF, 50V, +/- 10%, X7R, AEC-Q200 Grade 1, 0603	0603	06035C273K4T2A	AVX	
CD3	1	43 nF	Chip Multilayer Ceramic Capacitors for General Purpose, 0805, 43000pF, U2J, -750ppm/°C, 5%, 50V	FP-GRM21B-0_1-MFG	GRM21B7U1H433JA01L	Murata	
CD4	1	4300pF	Multilayer Ceramic Capacitor, C Series, 4300pF, - 5%, C0g / Np0, 50V, 0603 [1608 Metric] Rohs Compliant: Yes	FP-C0603C-CF-MFG	C0603C432J5GACTU	KEMET	
CF1	1	1000pF	CAP, CERM, 1000pF, 50V, +/- 5%, C0G/NP0, AEC-Q200 Grade 1, 0402	0402	CGA2B2C0G1H102J050BA	TDK	
CM1, CTEMP1	2	22pF	CAP, CERM, 22pF, 50V, +/- 5%, C0G/NP0, 0603	0603	06035A220JAT2A	AVX	
CO1	1	470uF	CAP, AL, 470uF, 25V, +/- 20%, SMD	CAPSMT_62_JA0	EMVE250ADA471MJA0G	Chemi-Con	
D1, D2	2		19.9V Clamp 150.8A Ipp Tvs Diode Surface Mount DO-214AB (SMCJ)	FP-SMDJ12A_DO214AB-MFG	SMDJ12A	Littelfuse Inc	
D3, D4	2	45V	Diode, Super Barrier Rectifier, 45V, 10A, PowerDI5	POWERDI5	SBR10U45SP5-13	Diodes Inc.	

Table 7-1. TPS25984BEVM Bill of Materials (continued)

Designator	Quantity	Value	Description	Footprint	PartNumber	Manufacturer	Comments
D5	1		Zener Diode 4.7V 250 mW ±1% Surface Mount TO-236AB	FP-BZX84-A4V7,215_SO T23-3-MFG	BZX84-A4V7,215	Nexperia	
DG1	1	Green	LED, Green, SMD	LG_R971_Green	LG R971-KN-1	OSRAM	
DR1, DR2	2	Red	LED, Red, SMD	LS_R976_Red	LS R976-NR-1	OSRAM	
G1, G2	2		1 mm Uninsulated Shorting Plug, 10.16mm spacing, TH	Harwin_D3082-05	D3082-05	Harwin	
H1, H2, H3, H4, H9, H10, H11, H12	8		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	NY PMS 440 0025 PH	NY PMS 440 0025 PH	B&F Fastener Supply	
H5, H6, H7, H8, H13, H14, H15, H16	8		Standoff, Hex, 0.5"L #4-40 Nylon	Keystone_1902C	1902C	Keystone	
J1, J8, J9	3		Header, 100mil, 3x1, Tin, TH	CONN_PEC03SAAN	PEC03SAAN	Sullins Connector Solutions	
J2	1		Header, 100mil, 3x2, Tin, TH	SULLINS_PEC03DAAN	PEC03DAAN	Sullins Connector Solutions	
J3, J4, J5, J6, J7	5			FP-PEC02DABN_HDR4-MFG	PEC02DABN	Sullins Connector Solutions	
Q1, Q2, Q3	3		N-Channel 30V 3.16A (Ta) 750mW (Ta) Surface Mount SOT-23-3 (TO-236)	FP-SI2306BDS-T1-GE3_SOT23-3-MFG	SI2306BDS-T1-GE3	Vishay Siliconix	
Q4, Q5, Q6	3	40V	MOSFET, N-CH, 40V, 42A, DNK0008A (VSON-CLIP-8)	DNK0008A	CSD18510Q5B	Texas Instruments	
QGND1	1		Test Point, Compact, SMT	Testpoint_Keystone_Compact	5016	Keystone	
R2	1	1.0Meg	RES, 1.0 M, 5%, 0.063 W, 0402	0402L	CRCW04021M00JNED	Vishay-Dale	
R3, R4, R5, R11, R12	5	10.0k	RES, 10.0k, 1%, 0.063 W, 0402	0402	RC0402FR-0710KL	Yageo America	
R6, R27	2	100k	RES, 100k, 1%, 0.1 W, AEC-Q200 Grade 0, 0603	0603	CRCW0603100KFKEA	Vishay-Dale	
R7	1	330k	RES, 330k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402	0402	CRCW0402330KFKED	Vishay-Dale	
R8, R10, R34, R35, R36	5	10	Res General Purpose Thick Film 0603 10 Ohm 5% 1/10W ±200ppm/°C Molded SMD Paper T/R	FP-RC0603JR-0710RL_0603-MFG	RC0603JR-0710RL	Yageo	
R9	1	121k	RES, 121k, 1%, 0.1 W, 0603	0603	RC0603FR-07121KL	Yageo	
R13, R14, R15	3	470	RES, 470, 5%, 0.1 W, 0603	0603	RC0603JR-07470RL	Yageo	
R16, R17, R18, R19, R20, R21	6	1	Res Wirewound 1 Ohm 5% 5W ±200ppm/°C Molded SMD T/R	FP-SMW51R0JT_5329-IPC_C	SMW51R0JT	TE Connectivity	
R22	1	10.0k	RES, 10.0k, 1%, 0.1 W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale	
R23	1	20.0k	RES, 20.0k, 1%, 0.1 W, 0603	0603	CRCW060320K0FKEA	Vishay-Dale	

Table 7-1. TPS25984BEVM Bill of Materials (continued)

Designator	Quantity	Value	Description	Footprint	PartNumber	Manufacturer	Comments
R25, R29	2	10k	RES, 10k, 5%, 0.1 W, 0603	0603	RC0603JR-0710KL	Yageo	
R26	1	49.9k	RES, 49.9k, 1%, 0.1 W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale	
R28	1	200k	RES, 200k, 1%, 0.1 W, 0603	0603	CRCW0603200KFKEA	Vishay-Dale	
RF1	1	40.2k	RES, 40.2k, 0.5%, 0.1 W, 0603	0603S	RT0603DRE0740K2L	Yageo America	
RF2	1	50k	High Precision-High Stability Chip Resistor Thin Film 0603 50kOhm 0.1% Paper T/R	FP-RT0603BRD0750KL_0603-MFG	RT0603BRD0750KL	Yageo	
RF3	1	100k	RES, 100k, 1%, 0.1 W, 0603	0603	RC0603FR-07100KL	Yageo	
RL2, RL4, RM3, RM4	4	1.8k	RES, 1.80k, 1%, 0.1 W, 0603	0603	RC0603FR-071K8L	Yageo	
RL3, RL5, RM5RM6	4	2.64k	RES, 2.64k, 0.1%, 0.1 W, 0603	0603	RT0603BRD072K64L	Yageo America	
RM7	1	0	RES, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale	
RZ1, RZ2, RZ4, RZ5, RZ6, RZ7, RZ8, RZ9	8	0	RES, 0, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	0402	CRCW04020000Z0ED	Vishay-Dale	
S1	1		Switch, SPST 5Pos, Rocker, TH	SW_76SB05	76SB05ST	Grayhill	
SH1, SH2, SH3, SH4, SH5, SH6, SH7, SH8	8		Shunt, 2.54mm, Gold, Blue	Wurth_60900213621	60900213621	Wurth Elektronik	
SW1, SW2, SW3	3		Tactile Switch SPST-NO Top Actuated Surface Mount	FP-PTS830GM140SMTRLFS_SM T_3MM05_2M M6-MFG	PTS830GM140SMTRLFS	C&K Components	
T1, T2, T3	3		1/0 AWG High AMP PCB Wire Lugs 1/0-8 AWG	FP-B1-0-PCB-L_WIRE_LUG_150A_1-0AWG-MFG	B1/0-PCB-L	INTERNATIONAL HYDRAULICS	
T4, T5	2		Connector, Receptacle, Pin, TH	CONN_0300-2-15-01-47-01-10-0	0300-2-15-01-47-01-10-0	Mill-Max	
TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20, TP21, TP22, TP23, TP24, TP25, TP26	26		Test Point, Multipurpose, Green, TH	Keystone5126	5126	Keystone	
TP27	1		Test Point, Multipurpose, Black, TH	Keystone5011	5011	Keystone Electronics	
U1, U2	2		4.5 - 16V, 0.8 mΩ, 50A Parallelizable eFuse with Accurate & Fast Current Monitor QFN32	RZJ0032A-MFG	TPS25984B0RZJR	Texas Instruments	
U3	1		100-mA, 30V, Fixed-Output, Linear-Voltage Regulator, DBZ0003A (SOT-23-3)	DBZ0003A_N	TLV76050DBZR	Texas Instruments	

Table 7-1. TPS25984BEVM Bill of Materials (continued)

Designator	Quantity	Value	Description	Footprint	PartNumber	Manufacturer	Comments
U4	1		Single-Channel High-Speed Low-Side Gate Driver with 5V Negative Input Voltage Handling Ability, DBV0006A (SOT-23-6)	DBV0006A_N	UCC27511AQDBVRQ1	Texas Instruments	
U5	1		Single Retriggerable Monostable Multivibrator with Schmitt-Trigger Inputs, YZP0008ADAD, LARGE T&R	YZP0008ADAD	SN74LVC1G123YZPR	Texas Instruments	
CO2	0	4700uF	CAP, AL, 4700uF, 25V, +/- 20%, TH	KMQ_1600x2500	EKMQ250EIV472ML25S	Chemi-Con	DNL
CT1	0	2200pF	CAP, CERM, 2200pF, 50V, +/- 5%, C0G/NP0, 0603	0603S	GRM1885C1H222JA01D	MuRata	DNL
FID1, FID2, FID3, FID4, FID5, FID6	0		Fiducial mark. There is nothing to buy or mount.	Fiducial6.4-20	N/A	N/A	DNL
R11, R12	0	10.0k	RES, 10.0k, 1%, 0.063 W, 0402	0402	RC0402FR-0710KL	Yageo America	DNL
R24	0	10k	RES, 10k, 5%, 0.1 W, 0603	0603	RC0603JR-0710KL	Yageo	DNL
RF1	0	40.2k	RES, 40.2k, 0.5%, 0.1 W, 0603	0603S	RT0603DRE0740K2L	Yageo America	DNL
RL1, RL6	0	402	RES, 402, 0.1%, 0.1 W, 0603	0603S	RT0603BRD07402RL	Yageo America	DNL
RM1	0	0	RES, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale	DNL
RM2	0	1.1k	1.1kOhms ±0.1% 0.1W, 1/10W Chip Resistor 0603 (1608 Metric) Anti-Sulfur, Automotive AEC-Q200, Moisture Resistant Thin Film	FP-TNPW06031K10BYEN_0603-MFG	TNPW06031K10BYEN	Vishay	DNL
RZ3	0	0	RES, 0, 5%, 0.063 W, AEC-Q200 Grade 0, 0402	0402	CRCW04020000Z0ED	Vishay-Dale	DNL

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1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
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 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
 - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
 - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
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WARNING

Evaluation Kits are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems.

User shall operate the Evaluation Kit within TI's recommended guidelines and any applicable legal or environmental requirements as well as reasonable and customary safeguards. Failure to set up and/or operate the Evaluation Kit within TI's recommended guidelines may result in personal injury or death or property damage. Proper set up entails following TI's instructions for electrical ratings of interface circuits such as input, output and electrical loads.

NOTE:

EXPOSURE TO ELECTROSTATIC DISCHARGE (ESD) MAY CAUSE DEGRADATION OR FAILURE OF THE EVALUATION KIT; TI RECOMMENDS STORAGE OF THE EVALUATION KIT IN A PROTECTIVE ESD BAG.

3 Regulatory Notices:

3.1 United States

3.1.1 Notice applicable to EVMs not FCC-Approved:

FCC NOTICE: This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。

<https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-delivered-in-japan.html>

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】 開発キットの中には技術基準適合証明を受けていないものがあります。技術適合証明を受けていないものご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。日本テキサス・イ

ンスツルメンツ株式会社

東京都新宿区西新宿 6 丁目 2 4 番 1 号

西新宿三井ビル

3.3.3 *Notice for EVMs for Power Line Communication:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_02.page

電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。 <https://www.ti.com/ja-jp/legal/notice-for-evaluation-kits-for-power-line-communication.html>

3.4 European Union

3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

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4. *EVM Use Restrictions and Warnings:*
 - 4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.
 - 4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
 - 4.3 *Safety-Related Warnings and Restrictions:*
 - 4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.
 - 4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.
 - 4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.
 5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.
 6. *Disclaimers:*
 - 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
 - 6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.
 7. *USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.* USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.
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8. *Limitations on Damages and Liability:*

8.1 *General Limitations.* IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS , REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.

8.2 *Specific Limitations.* IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, , EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.

9. *Return Policy.* Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.

10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

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